



DRAFT

Product Change Notice (PCN)

PCN #: VI0801090

Date: January 9th 2008

To Our Valued Customers:

We appreciate your use of V•I Chip products. Our commitment to customer satisfaction and continuous improvement is demonstrated by our plans to enhance quality, reliability and manufacturability. The purpose of this notice is to inform you of a product change.

PCN Type:

Product function

Product(s) Affected:

All V•I Chip PRMs, BCMs, and VTMs

Phase 1:

P045F048T32AL

VIZ0017

V048F015T100

V045F020T80

Phase 2:

All remaining V•I Chips

Changes:

Enhanced cleaning techniques to improve product mechanical integrity (all products)
New components for higher design margins to improve manufacturing yields (VTMs).
Automated core-gapping adhesive (Phase 1 VTMs).

Reason(s) for the Change:

The changes are being implemented to further enhance manufacturability & reliability.
In the case of core-gapping adhesive, the change updates the process from an obsoleted, manually applied adhesive to a next generation automatically dispensed material.

Customer impact:

For Phase 1 VTMs (above), there is a small increase in no-load power dissipation. Please refer to datasheets for details.

For Phase 1 PRMs, the process updates have negligible change to performance and the datasheets remain unchanged.

For Phase 2 (all remaining PRMs, VTMs and BCMs), no performance changes are expected. This will be confirmed in an update to this PCN once the Phase 2 change date is known.

Effective dates of change:

Phase 1: 3rd March 2008 (product date code 0810 and onwards). Samples are available now.

Phase 2: To be determined (will be later than 1st April 2008)

Note that the Phase 1 date is driven by the obsolescence of the core-gapping adhesive.



An update to this PCN will be distributed when the Phase 2 date has been determined.

For further information, please contact:

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